

DATASHEET

SMD • A 91-21SDRC/S530-XX/XXX



Features

- Package in 12mm tape on 7" diameter reel.
- · Compatible with automatic placement equipment.
- EIA Std. package.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Description

• The SMD LED is much smaller than leaded components .

Thus enable smaller board size. Higher packing density. Reduced storage space and finally smaller equipment to be obtained.

- Besides, light weight makes them ideal for miniature applications.
- Furthermore by automation assembly machines the accuracy is anticipated.

Applications

- Small indicator for indoor applications.
- Flat backlight for LCD, switches and symbols.
- Indicator and backlight in office equipment.
- Indicator and backlight for battery driven equipment.
- Indicator and backlight for audio and video equipment.
- · Backlighting in dashboards and switches.
- Telecommunication: indicator and backlighting in telephone and fax.



Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGalnP	Deep Red	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V_R	5	V	
Forward Current	l _F	20	mA	
Peak Forward Current (Duty 1/10 @1KHz)	lгр	60	mA	
Power Dissipation	Pd	60	mW	
Operating Temperature	T_{opr}	-40 ~ +85	$^{\circ}\mathbb{C}$	
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\mathbb{C}$	
Electrostatic Discharge	ESDнвм	2000	V	
Soldering Temperature	T _{sol}	Reflow Soldering : 260 $^{\circ}\mathbb{C}$ for 10 sec. Hand Soldering : 350 $^{\circ}\mathbb{C}$ for 3 sec.		

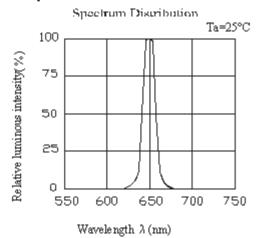
Electro-Optical Characteristics (Ta=25°C)

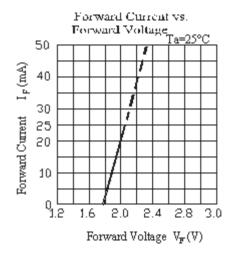
Parameter	Symbol	Rank	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	A2	198	350		— — mcd —	
		A3	330	495			1. 00 · A
		A4	396	980			
		A5	529	1028			
		A6	661	1232			
Viewing Angle	2θ _{1/2}			25		deg	I _F =20mA
Peak Wavelength	λр			650		nm	
Dominant Wavelength	λd			639		nm	
Spectrum Radiation Bandwidth	Δλ			20		nm	
Forward Voltage	VF	·	1.7	2.0	2.4	V	
Reverse Current	I_R				10	μΑ	V _R =5V

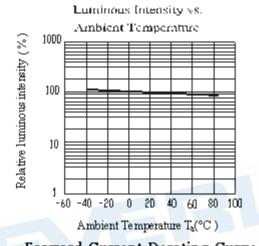
Notes:

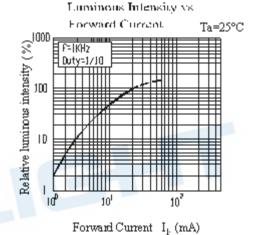
^{1.} Reverse Voltage(VR) Condition is applied to IR test only The device is not designed for reverse operation

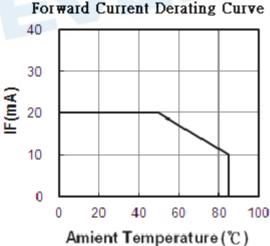
Typical Electro-Optical Characteristics Curves

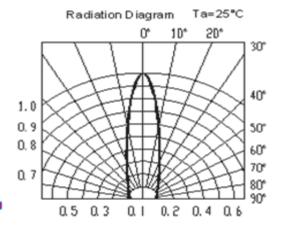




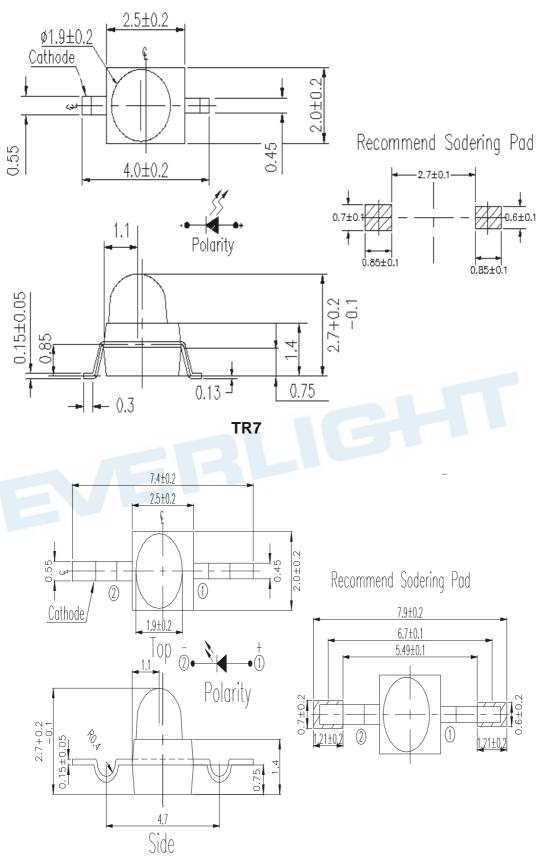




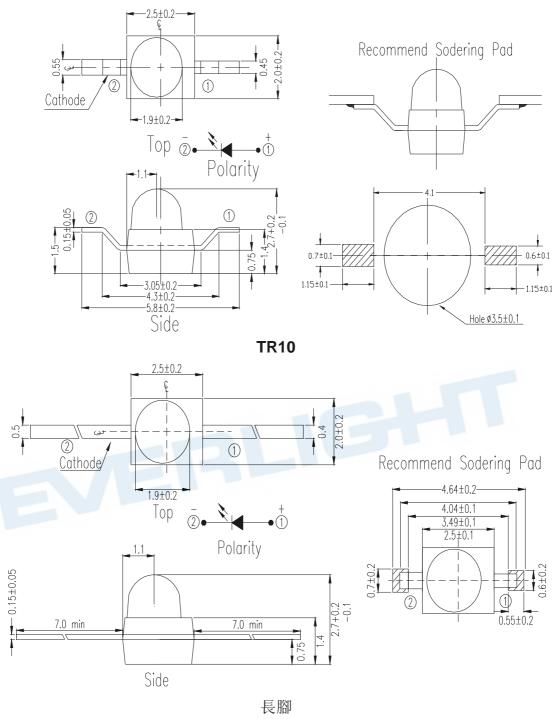




Package Outline Dimensions



TR9



Suggested pad dimension is just for reference only. Please modify the pad dimension based on individual need.

Note: The tolerances unless mentioned are ±0.1, unit=mm.



Package Outline Dimensions

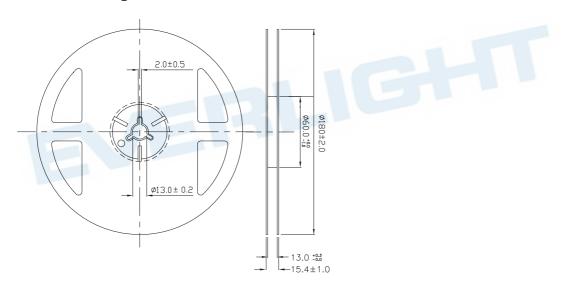
Label Explanation



MADE IN XXXXXX

- · CPN: Customer's Product Number
- P/N: Product NumberLOT No: Lot NumberQTY: Packing Quantity
- CAT: Luminous Intensity RankHUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank

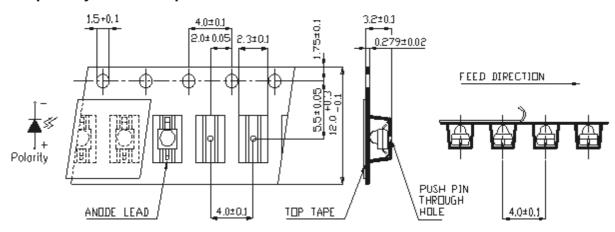
Reel & Carrier Tape Dimensions

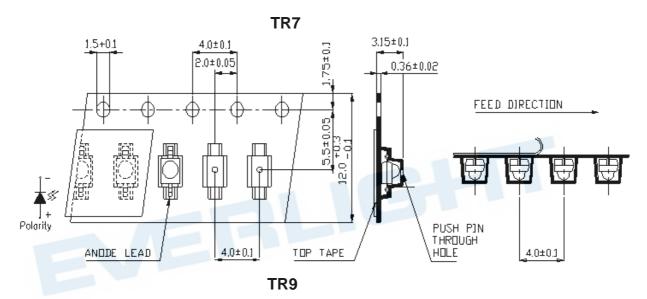


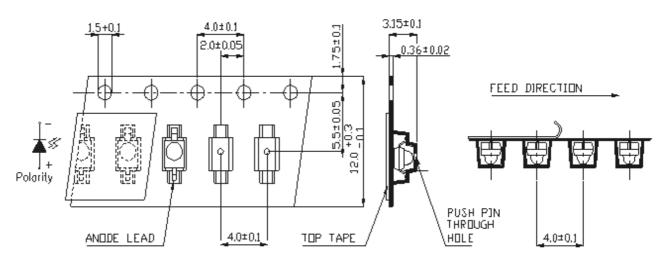
Note: The tolerances unless mentioned are ±0.1, unit=mm.



Loaded quantity 1000 PCS per reel



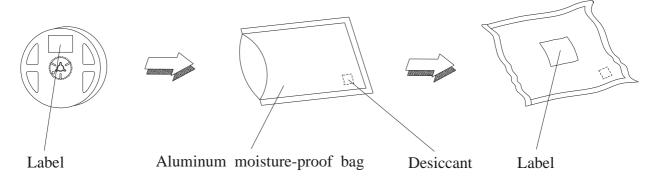




TR10



Moisture Resistant Packaging



Precautions For Use

1. Over-current-proof

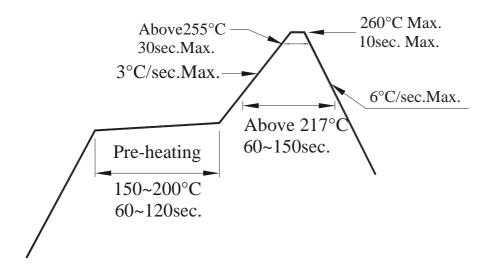
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

- 2. Storage
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 72 hours under 30℃ or less and 60% RH or less.

 If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

- 3. Soldering Condition
- 3.1 Pb-free solder temperature profile



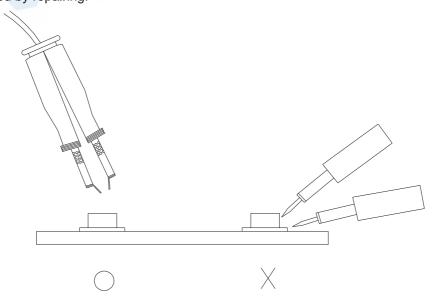
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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